		T				ı			T
PCN Number:		20161230000					PCN Date:		Jan. 4, 2017
Title:	Datasheet fo	r TPS53311							
Customer Contact: PCN Manage			<u>r</u>			D	Dept: Qua		lity Services
Change	е Туре:								
Assembly Site		Design				Wafer Bump Site			
Assembly Process		□ Data Sheet					Wafer Bump Material		
Assembly Materials				er change	Wafer Bump Process				
Mechanical Specification		Ļ	Test Site		ļĻ	Wafer Fab Site			
Packing/Shipping/Labeling			Test Proce	ess ess	4 <u>L</u>	Wafer Fab Materials Wafer Fab Process			
							_ Wafe	r Fab	Process
			N	otificatio	n Details				
	otion of Chang								
					information or		notificati	on.	
The product datasheet(s) is being updated as summarized below. The following change history provides further details.									
The follo	owing change i	listory provid	ies	iuitiiei deta	illS.				
₹ /3	Texas								70.50044
•	INSTRUMENTS TPS53311 SLUSA41B – JUNE 2010 – REVISED SEPTEMBER 2016								
					SEOSATIE	5-501	4E 2010-NEVI	OLD OLI I	LINDLIN 2010
Changes	from Revision A (Mar	rch 2011) to Revision	on B					Page	
 Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 									
	Deleted Ordering Information table; see POA at the end of the data sheet								
 Added 									
	Doctor Turning Disciplina Thairing and								
	Changed value of component R2 in Typical Application Circuit Diagram From: 4.02 kΩ To: 2.67 kΩ								
	Changed value of component V _{OUT} on TPS53311 Master in Master and Slave Configuration Schematic From: 1.2 V To: 1.5 V								
Changed value of component R2 on TPS53311 Master in Master and Slave Configuration Schematic From: 4.02 kΩ To: 2.67 kΩ									
	Changed value of component V _{OUT} on TPS53311 Slave in <i>Master and Slave Configuration Schematic</i> From: 1.5 V To: 1.2 V								
 Changed value of component R12 on TPS53311 Slave in Master and Slave Configuration Schematic From: 2.67 kΩ 									
To: 4.02 kΩ									
The dat	asheet number	will be chan	ain	٦					
Device Family		Will be chair	Change From:					Chan	ge To:
	TPS53311			SLUSA41A					5A41B
		e reviewed at	the		links provided.	ı			
http://v	www.ti.com/pro	duct/TPS533	11						
Reasor	for Change:								
To more	e accurately ref	lect device cl	hara	acteristics.					
Anticip	ated impact of	on Fit, Form	, Fu	ınction, Qı	uality or Relia	bili	ty (pos	itive	/ negative):
No anticipated impact. This is a specification change announcement only. There are no changes									
to the actual device.									
Change	es to product	identificatio	n n	esulting f	om this PCN:				
None.	<u>-</u>								
Produc	t Affected:								
	311RGTR	TPS53311	RG	П]				
, <u></u>	- · · · · · ·				1				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
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Japan	PCNJapanContact@list.ti.com